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AMENDMENTS TO THE CLAIMS

1. (Previously presented) A light-emitting diode (LED) lamp comprising:

a substrate coated with a metal pattern formed as an electrically conducting portion including films of copper (Cu), nickel (Ni) and gold (Au) laminated successively in this order on the substrate;

a resin frame member fixed onto the substrate through an adhesive agent;

a light-emitting element fixed into a frame of the resin frame member on the substrate so as to be electrically connected to the metal pattern;

a resist bonded onto a nickel-free or gold-free surface of the copper film of the metal pattern to form such a structure that the resist is at least partially formed between the substrate and the resin frame member; and

a light-transmissive resin packed in the frame of the resin frame member to seal the light-emitting element with the light-transmissive resin.

2. (Original) An LED lamp according to Claim 1, wherein an inner edge of the resist held between the resin frame member and the substrate is visible from the edge of the through-hole of the resin frame member.

3. (Previously presented) An LED lamp according to Claim 1, wherein the resist comprises a ring shape.

4-5. (Canceled)

6. (Previously presented) An LED lamp according to Claim 1, wherein said resin frame member comprises a nylon resin.

7. (Previously presented) An LED lamp according to Claim 1, wherein said resist comprises a resist for adhering said resin frame member to said metal pattern.

8. (Previously presented) An LED lamp according to Claim 1, wherein an inner surface of said resin frame member comprises a reflective surface for reflecting light emitted from said light-emitting element.

9. (Previously presented) An LED lamp according to Claim 1, wherein said light-emitting element comprises an electrode that is wire bonded to said metal pattern.

10. (Previously presented) An LED lamp according to Claim 1, wherein said light-transmissive resin comprises an epoxy resin.

11. (Previously presented) An LED lamp according to Claim 1, wherein said adhesive agent is formed on said resist and said metal pattern.

12. (Previously presented) An LED lamp according to Claim 1, wherein said resin frame member is bonded to said resist and said metal pattern via said adhesive agent.

13. (Previously presented) An LED lamp according to Claim 1, wherein said surface of said copper film comprises irregularities for increasing a contact area between said resist and said surface of said copper film.

14. (Previously presented) An LED lamp according to Claim 1, wherein said light-emitting element comprises a flip-chip type light emitting element.

15. (Currently amended) A light-emitting diode (LED) lamp comprising:

a metal pattern formed on a substrate and comprising a copper layer and a nickel layer formed on a surface of said copper layer;

a resist layer directly bonded to said ~~a~~ surface of said copper layer;

a light-emitting element formed on said substrate and electrically connected to said metal

pattern; and

a frame member formed outside said light-emitting element, at least a portion of said frame member being formed on said resist layer.

16. (Currently amended) An LED lamp according to Claim 15, wherein said metal pattern further comprises ~~a nickel layer formed on said copper layer and~~ a gold layer formed on said nickel layer.

17. (Currently amended) An LED lamp according to Claim 16 ~~15~~, wherein said gold layer and said nickel layer are formed on a side surface of said resist layer.

18. (Previously presented) An LED lamp according to Claim 15, wherein at least a portion of said resist layer is formed between said substrate and said frame member.

19. (Previously presented) An LED lamp according to Claim 15, further comprising:
a light-transmissive resin formed on said substrate and sealing said light-emitting element.

20. (Previously presented) An LED lamp according to Claim 15, further comprising:
an adhesive layer formed between said resist layer and said frame member.

21. (Previously presented) An LED lamp according to Claim 15, wherein said copper layer comprises a lowermost layer of said metal pattern.

22. (Currently amended) A lamp structure for a light-emitting element, said lamp structure comprising:
a substrate on which said light-emitting element is mounted;
a metal pattern formed on said substrate and comprising a copper layer and a nickel layer formed on a surface of said copper layer;

a resist layer directly bonded to said a surface of said copper layer; and

a frame member formed outside said light-emitting element, at least a portion of said frame member being formed on said resist layer.

23. (Previously presented) An LED lamp according to Claim 15, wherein said resist layer reaches other than an exterior side surface of the frame member.

24. (Previously presented) A lamp structure according to Claim 22, wherein said resist layer reaches other than an exterior side surface of the frame member.

25. (New) An LED lamp according to Claim 15, wherein at least a portion of said frame member is formed on said nickel layer of said metal pattern.

26. (New) A light-emitting diode (LED) lamp comprising:

a metal pattern formed on a substrate and comprising a copper layer and a plating layer laminated on a surface of said copper layer;

a resist layer directly bonded to said surface of said copper layer;

a light-emitting element formed on said substrate and electrically connected to said metal pattern; and

a frame member formed outside said light-emitting element, at least a portion of said frame member being formed on said resist layer.

27. (New) The light-emitting diode (LED) lamp according to claim 26, wherein an uppermost layer of the laminated plating layer comprises a metal having a solder wettability that is greater than a solder wettability of copper.

28. (New) The light-emitting diode (LED) lamp according to claim 27, wherein said metal having a solder wettability that is greater than a solder wettability of copper comprises gold.